

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3209239

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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Name	Execution Date
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13877884
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DATE SIGNED:	02/03/2015
Total Attachments: 2	
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UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

WHEREAS I, Soung Hwi PARK of 8F, 802 Daechi-dong, Yeongdongdaero 330, Gangnam-gu, Seoul 135-851, Republic of Korea (hereinafter referred to as "ASSIGNOR") is the owner of the entire right, title and interest in the following United States Patent Application:

U.S. Patent Application No.: 13/877,884

Application Filing Date: April 4, 2013

Title: LIGHT-EMITTING DIODE DRIVING CIRCUIT FOR LIGHTING

WHEREAS, POWER CHIPS CO., LTD. (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Korea, having a place of business at 8F, 802 Daechi-dong, Yeongdongdaero 330, Gangnam-gu, Seoul 135-851, Republic of Korea, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations,

continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and I do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that I will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

In WITNESS WHEREOF, the Assignor has caused this Assignment to be executed by its duly authorized officer this 26 day of JAN, 2015.

By: Park Seung Hwi
[sign above]

Name: Seung Hwi PARK
[print name above]